RENESAS

R1LP0108E Series

1Mb Advanced LPSRAM (128k word x 8bit)

R10DS0270EJ0200 Rev.2.00 2019.10.29

Description

The R1LP0108E Series is a family of low voltage 1-Mbit static RAMs organized as 131,072-word by 8-bit, fabricated by Renesas's high-performance 0.15um CMOS and TFT technologies. The R1LP0108E Series has realized higher density, higher performance and low power consumption. The R1LP0108E Series is suitable for memory applications where a simple interfacing, battery operating and battery backup are the important design objectives. It has been packaged in 32-pin SOP, 32-pin TSOP and 32-pin sTSOP.

Features

- Single 4.5V~5.5V power supply
- Small stand-by current: 0.6µA (5.0V, typical)
- No clocks, No refresh
- All inputs and outputs are TTL compatible.
- Easy memory expansion by CS1# and CS2
- Common Data I/O
- Three-state outputs: OR-tie Capability
- OE# prevents data contention on the I/O bus

Ordering Information

Orderable part name	Access time	Temperature range	Package	Shipping container
R1LP0108ESN-5SI#B*			525-mil 32-pin	Tube (Magazine)
R1LP0108ESN-5SI#S*			plastic SOP	Embossed tape
R1LP0108ESA-5SI#B*	55 ns	-40 ∼ +85°C	8mm×13.4mm 32-pin	Tray
R1LP0108ESA-5SI#S*	55 HS	-40 ~ +65 C	plastic sTSOP	Embossed tape
R1LP0108ESF-5SI#B*			8mm×20mm 32-pin	Tray
R1LP0108ESF-5SI#S*			plastic TSOP	Embossed tape

Note 1. * = Revision code for Assembly site change, etc. (* = 0, 1, etc.)



Pin Arrangement

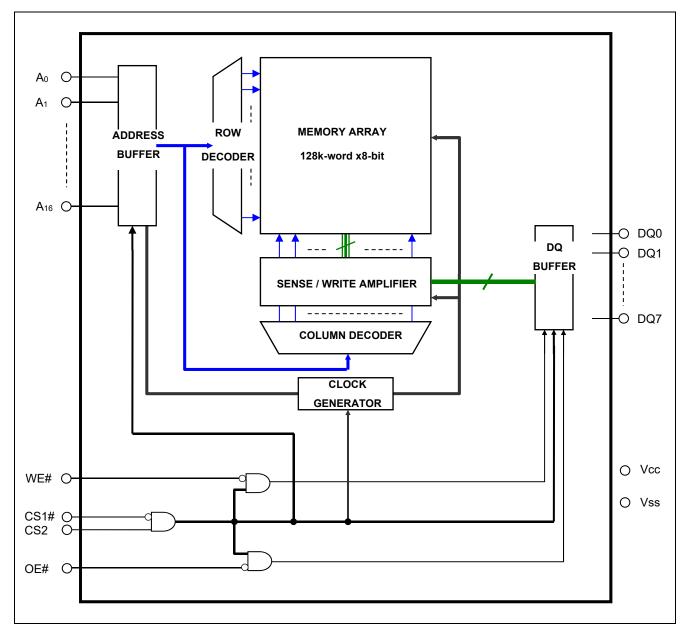
NC 32 1 Vcc A16 2 31 A15 3 CS2 A14 30 A12 4 29 WE# 5 28 A13 A7 6 27 A6 A8 A5 7 26 A9 32-pin SOP 25 A11 **A**4 8 **A**3 9 24 OE# 10 A2 23 A10 **A1** 11 22 CS1# 12 21 DQ7 A0 13 DQ6 DQ0 20 DQ1 14 19 DQ5 DQ2 15 18 DQ4 GND 16 17 DQ3 A11 32 OE# 1 A9 2 31 A10 **A**8 3 30 CS1# A13 4 29 DQ7 WE# 28 DQ6 5 CS2 6 27 DQ5 A15 26 DQ4 7 32-pin sTSOP Vcc 8 25 DQ3 NC 9 24 GND A16 10 23 DQ2 A14 11 22 DQ1 A12 12 21 DQ0 A7 13 20 A0 A6 14 19 **A**1 A5 15 18 A2 **A**4 16 17 A3 A11 OE# 1 32 A9 2 31 A10 **A**8 3 30 CS1# A13 4 29 DQ7 WE# 5 28 DQ6 CS2 27 DQ5 6 A15 7 26 DQ4 Vcc 32-pin TSOP 8 DQ3 25 NC 9 24 GND A16 DQ2 10 23 A14 DQ1 11 22 A12 12 21 DQ0 A7 13 20 A0 A6 14 19 **A**1 A5 15 18 A2 **A**4 16 17 A3



Pin Description

Pin name	Function
Vcc	Power supply
Vss (GND)	Ground
A0 to A16	Address input
DQ0 to DQ7	Data input/output
CS1#	Chip select 1
CS2	Chip select 2
WE#	Write enable
OE#	Output enable
NC	Non connection

Block Diagram



Operation Table

CS1#	CS2	WE#	OE#	DQ0~7	Operation
Х	L	Х	Х	High-Z	Stand-by
Н	Х	Х	Х	High-Z	Stand-by
L	Н	L	Х	Din	Write
L	Н	Н	L	Dout	Read
L	Н	Н	Н	High-Z	Output disable

Note 1. H: V_{IH} L:V_{IL} X: V_{IH} or V_{IL}

Absolute Maximum

Parameter	Symbol	Value	unit
Power supply voltage relative to Vss	Vcc	-0.3 to +7.0	V
Terminal voltage on any pin relative to Vss	VT	-0.3 ^{*1} to Vcc+0.3 ^{*2}	V
Power dissipation	Pτ	0.7	W
Operation temperature	Topr	-40 to +85	°C
Storage temperature range	Tstg	-65 to 150	°C
Storage temperature range under bias	Tbias	-40 to +85	°C

Note 1. -3.0V for pulse ≤ 30 ns (full width at half maximum)

2. Maximum voltage is +7.0V.



DC Operating Conditions

Parameter	Symbol	Min.	Тур.	Max.	Unit	Note
Supply voltage	Vcc	4.5	5.0	5.5	V	
	Vss	0	0	0	V	
Input high voltage	VIH	2.2	-	Vcc+0.3	V	
Input low voltage	VIL	-0.3	-	0.8	V	1
Ambient temperature range	Та	-40	-	+85	°C	

Note 1. -3.0V for pulse ≤ 30 ns (full width at half maximum)

DC Characteristics

Parameter	Symbol	Min.	Тур.	Max.	Unit	Test conditions		
Input leakage current	I∟ı	-	-	1	μA	Vin = Vss to Vcc		
Output leakage current	Ilo	-	-	1	μA	CS1# =V _{IH} or CS2 =V _{IL} or OE# =V _{IH} , VI/O =Vss to Vcc		
Average operating current	Icc1	-	25	35	mA	-	, duty =100%, II/O = 0mA, , CS2 =V _{IH} , Others = V _{IH} /V _{IL}	
	Icc2	-	2	5	mA	Cycle =1µs, duty =100%, II/O = 0mA, CS1# ≤ 0.2V, CS2 ≥ Vcc-0.2V, V _{IH} ≥ Vcc-0.2V, V _{IL} ≤ 0.2V		
Standby current	Isb	-	-	3	mA	"CS2 =V _{IL} " or "CS2 = V _{IH} and CS1# =V _{IH} ", Others = Vss to Vcc		
Standby current		-	0.6 ^{*1}	2	μA	~+25°C	Vin = Vss to Vcc,	
	las i	-	-	3	μΑ	~+40°C	(1) $CS2 \le 0.2V$ or	
	Isb1	-	-	8	μA	~+70°C	(2) CS1# ≥ Vcc-0.2V, CS2 ≥ Vcc-0.2V	
		-	-	10	μA	~+85°C		
Output high voltage	Vон	2.4	-	-	V	I _{он} = -1mA		
	V _{OH2}	Vcc - 0.5	-	-	V	I _{OH} = -0.1mA		
Output low voltage	Vol	-	-	0.4	V	I _{OL} = 2mA		

Note 1. Typical parameter indicates the value for the center of distribution at 5.0V (Ta= 25°C), and not 100% tested.

Capacitance

(Vcc = 4.5V ∼ 5.5V, f = 1MHz, Ta = -40 ∼ +85°0							
Symbol	Min.	Тур.	Max.	Unit	Test conditions	Note	
C in	-	-	8	pF	Vin =0V	1	
C 1/0	-	-	10	pF	VI/O =0V	1	
	C in	Symbol Min. C in -	Symbol Min. Typ.	SymbolMin.Typ.Max.C in8	Symbol Min. Typ. Max. Unit C in - - 8 pF	Symbol Min. Typ. Max. Unit Test conditions C in - - 8 pF Vin =0V	

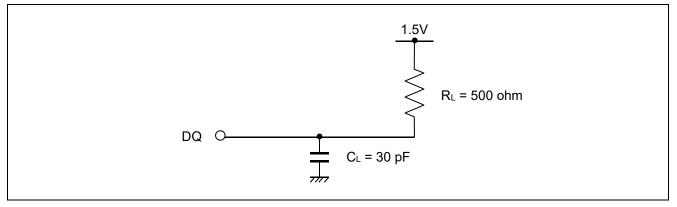
Note 1. This parameter is sampled and not 100% tested.



AC Characteristics

Test Conditions (Vcc = $4.5V \sim 5.5V$, Ta = $-40 \sim +85^{\circ}C$)

- Input pulse levels: VIL = 0.6V, VIH = 2.4V
- Input rise and fall time: 5ns
- Input and output timing reference level: 1.5V
- Output load: See figures (Including scope and jig)





Read Cycle

Parameter	Symbol	Min.	Max.	Unit	Note
Read cycle time	t _{RC}	55	-	ns	
Address access time	taa	-	55	ns	
Chin coloct access time	t _{ACS1}	-	55	ns	
Chip select access time	t _{ACS2}	-	55	ns	
Output enable to output valid	toe	-	30	ns	
Output hold from address change	toн	5	-	ns	
Chin colort to output in low 7	t _{CLZ1}	5	-	ns	2,3
Chip select to output in low-Z	t _{CLZ2}	5	-	ns	2,3
Output enable to output in low-Z	tolz	5	-	ns	2,3
Chin decalest to subsut in high 7	t _{CHZ1}	0	20	ns	1,2,3
Chip deselect to output in high-Z	t _{CHZ2}	0	20	ns	1,2,3
Output disable to output in high-Z	tонz	0	20	ns	1,2,3

Write Cycle

Parameter	Symbol	Min.	Max.	Unit	Note
Write cycle time	twc	55	-	ns	
Address valid to end of write	taw	50	-	ns	
Chip select to end of write	tcw	50	-	ns	5
Write pulse width	t _{WP}	45	-	ns	4
Address setup time	t _{AS}	0	-	ns	6
Write recovery time	twR	0	-	ns	7
Data to write time overlap	t _{DW}	25	-	ns	
Data hold from write time	t _{DH}	0	-	ns	
Output enable from end of write	tow	5	-	ns	2
Output disable to output in high-Z	tонz	0	20	ns	1,2
Write to output in high-Z	twнz	0	20	ns	1,2

Note 1. t_{CHZ}, t_{OHZ} and t_{WHZ} are defined as the time at which the outputs achieve the open circuit conditions and are not referred to output voltage levels.

- 2. This parameter is sampled and not 100% tested.
- 3. At any given temperature and voltage condition, t_{HZ} max is less than t_{LZ} min both for a given device and from device to device.

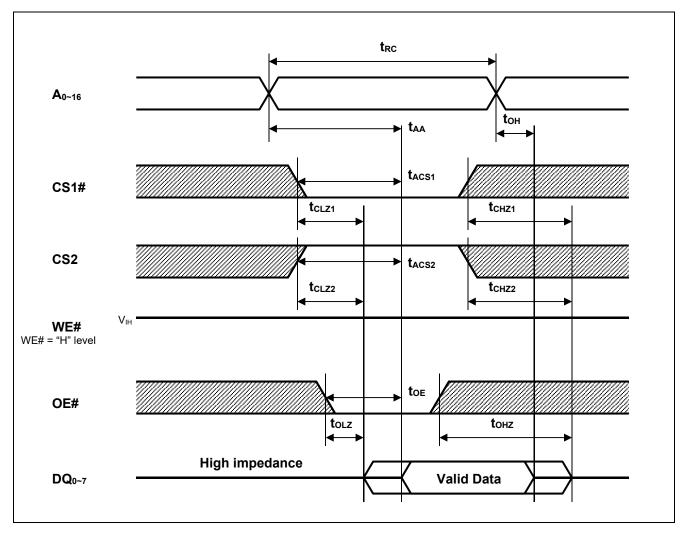
4. A write occurs during the overlap of a low CS1#, a high CS2, a low WE#.
A write begins at the latest transition among CS1# going low, CS2 going high and WE# going low.
A write ends at the earliest transition among CS1# going high, CS2 going low and WE# going high.
t_{WP} is measured from the beginning of write to the end of write.

- 5. t_{CW} is measured from the later of CS1# going low or CS2 going high to end of write.
- 6. t_{AS} is measured the address valid to the beginning of write.
- 7. twR is measured from the earliest of CS1# or WE# going high or CS2 going low to the end of write cycle.
- 8. Don't apply inverted phase signal externally when DQ pin is output mode.



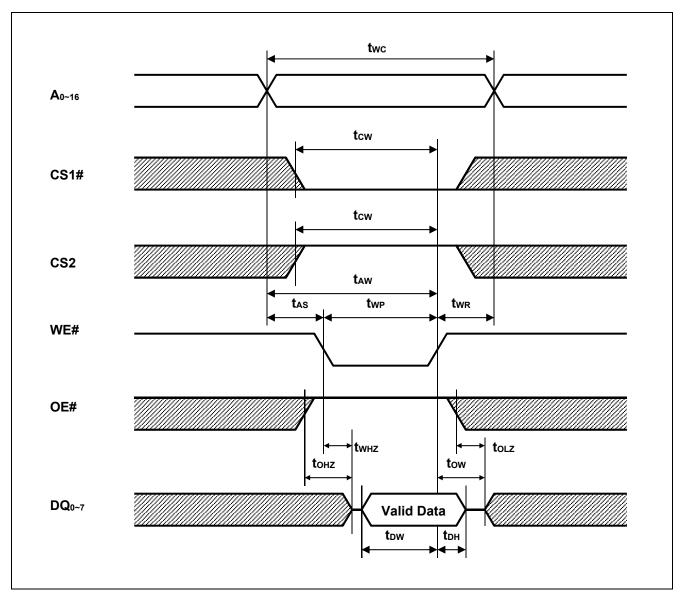
Timing Waveforms

Read Cycle



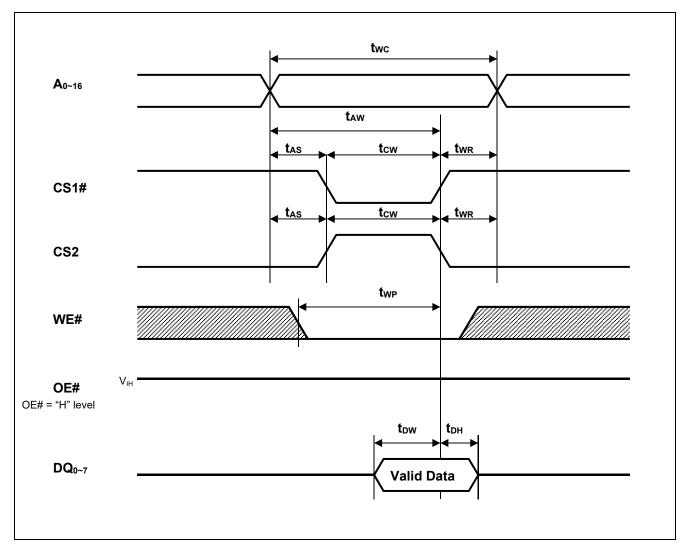


Write Cycle (1) (WE# CLOCK)





Write Cycle (2) (CS1#, CS2 CLOCK)



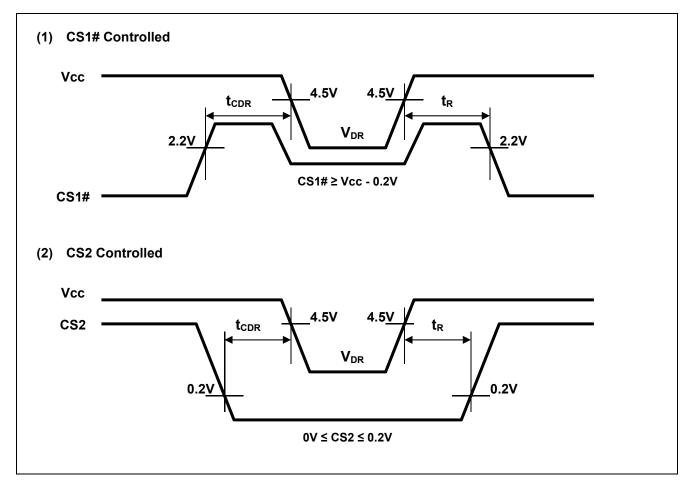


Parameter	Symbol	Min.	Тур.	Max.	Unit	Test conditions ^{*2}		
V _{CC} for data retention	Vdr	2.0	-	5.5	V	$Vin \ge 0V,$ $(1) \ 0V \le CS2 \le 0.2V \text{ or}$ $(2) \ CS1\# \ge Vcc-0.2V,$ $CS2 \ge Vcc-0.2V$		
	ICCDR	-	0.6 ^{*1}	2	μA	~+25°C	Vcc=3.0V, Vin ≥ 0V,	
Data retention current		-	-	3	μA	~+40°C	(1) 0V ≤ CS2 ≤ 0.2V or	
Data retention current		-	-	8	μA	~+70°C	(2) CS1# ≥ Vcc-0.2V, CS2 ≥ Vcc-0.2V	
		-	-	10	μA	~+85°C		
Chip deselect time to data retention	t _{CDR}	0	-	-	ns			
Operation recovery time	t _R	5	-	-	ms	See retention waveform.		

Note 1. Typical parameter indicates the value for the center of distribution at 3.0V (Ta= 25°C), and not 100% tested.

CS2 controls address buffer, WE# buffer, CS1# buffer, OE# buffer and Din buffer. If CS2 controls data retention mode, Vin levels (address, WE#, CS1#, OE#, DQ) can be in the high impedance state.
 If CS1# controls data retention mode, CS2 must be CS2 ≥ Vcc-0.2V or 0V ≤ CS2 ≤ 0.2V. The other input levels (address, WE#, OE#, DQ) can be in the high impedance state.

Low Vcc Data Retention Timing Waveforms



R1LP0108E Series Data Sheet

		Description	
Rev.	Date	Page	Summary
1.00	2017.1.27	-	First Edition issued
2.00	2019.10.29	p.1	Revised orderable part name information.

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